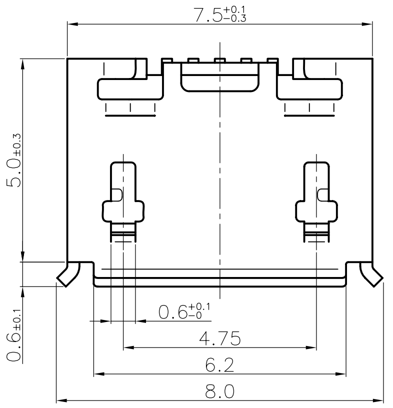
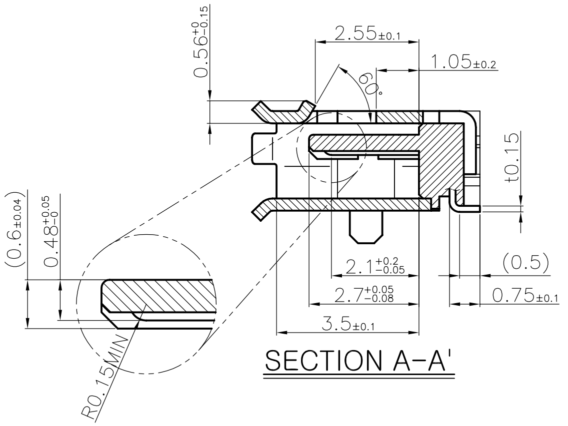
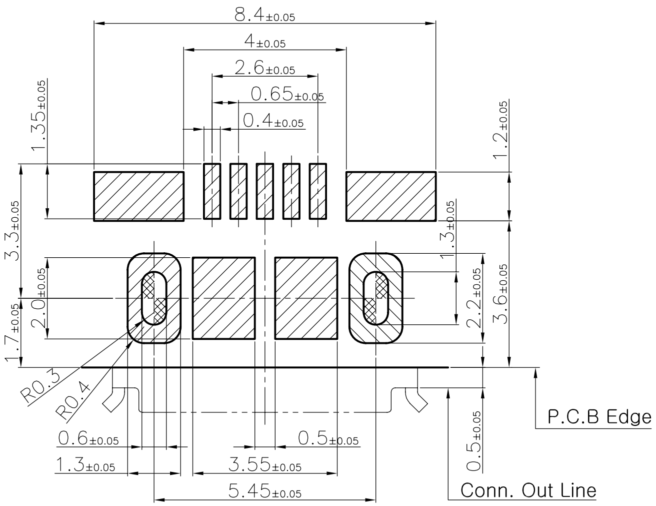
Rev No.	Description of Revision	Date	Name	Approved	ECN No.
△1	Transfer of SMD Position (DIP)	07.07.25	Lee		

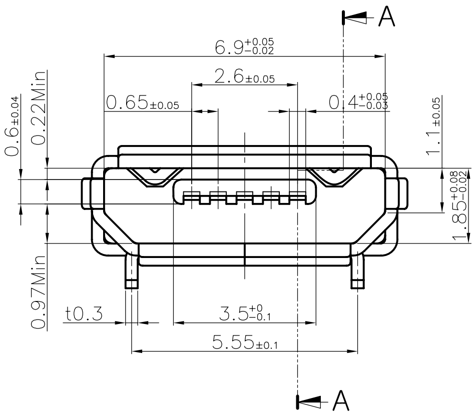


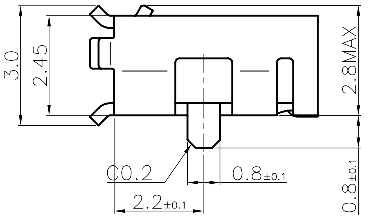


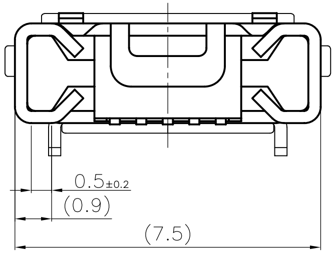
SECTION A-A'



P.C.B LAYOUT





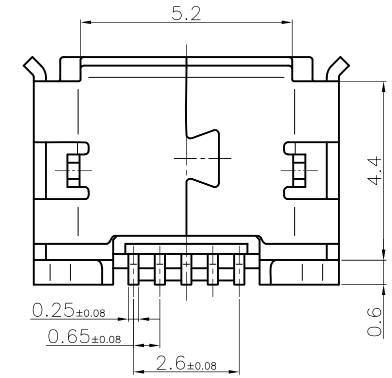


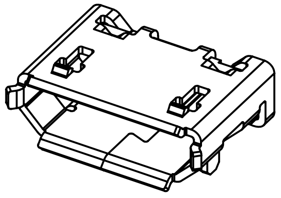
※ Specifications

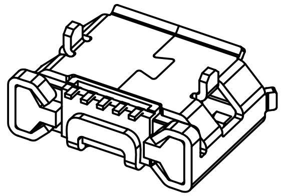
1. Voltage Rating : 30V_{AC}/DC
2. Current Rating : 1.0A/Pin
3. Operating temperature : -30℃~+80℃
4. Insertion Force : 3.5Kgf Max
5. Extraction Force : 0.8Kgf Min(After 10K cycles)
6. Durability : 10,000 cycles

※ NOTE

1. PLATING
   1) CONTACT
      - Contact Area : Au 0.75㎛ Min over Ni 2.0 Min
      - Lead Area : Au 0.05㎛ Min over Ni 0.2 Min
   2) METAL COVER : Ni 1.0 Min
2. COPLANARITY : 0.08 MAX







무단복사복제금지
出圖
2007.08.29
유효
HYUP JIN I&C CO., LTD.

No	Descriptions	Material	Finish	Remarks
3	METAL COVER	STS304	Note. 1	t0.3
2	CONTACT	C5210	Note. 1	t0.15
1	HOUSING	PA9T	Black Color	UL94V-0

General Tolerance	
Dimension	mm (°)
X	± 0.2
X.X	± 0.1
X.XX	± 0.05
X.XXX	± 0.01
ANGLE	± 1°

Scale N/S
Units mm
Sheet 1 of 1
Date 2007. 02. 10

Drawn	Design	Checked	Reviewed	Approved
M. Y. LEE				

HJI&C HYUP JIN I&C CO., LTD.

TITLE HI05-AG0250
Micro-USB Socket (B)
Customer Drawing

SW No.
DWG No. HI05-AG0250-A1
Rev. 1